Introduction

Thank you for participating in the Virtex®-7 FPGAs Engineering Sample Program. As part of this program, we are pleased to provide to you engineering samples of the devices listed in Table 1. Although Xilinx has made every effort to ensure the highest possible quality, these devices are subject to the limitations described in the following errata.

Devices

These errata apply to the devices shown in Table 1.

Table 1: **Devices Affected by These Errata**

Product Family	Device	JTAG ID (Revision Code)	Packages	Speed Grades
Virtex-7	XC7VX485T CES	2	All	-1, -2

Hardware Errata Details

This section provides a detailed description of each hardware issue known at the release time of this document.

XADC

For improved linearity, a new BitGen option (XADCEnhancedLinearity = ON¦OFF) must be set to ON (see Answer Record 45781 for more information). The specifications enhanced by this BitGen option are INL, THD, and SNR (see Table 2). By default this BitGen option is set to OFF. Existing XADC designs operate with the OFF setting.

Table 2 also lists errata for XADC DC accuracy specifications of Offset Error, Gain Error, Channel Matching, and On-Chip Reference Variation.

Table 2: **XADC Errata**

Parameter	XADC Errata		DS183 (v1.2), *Virtex-7 FPGAs Data Sheet: DC and Switching Characteristics Specifications*
	XADCEnhancedLinearity = ON	**XADCEnhancedLinearity = OFF**	
Integral Nonlinearity (INL)	±3 LSBs Max	±5 LSBs Max	±2 LSBs Max
Total Harmonic Distortion (THD)	65 dB Typ	65 dB Typ	75 dB Min
Signal to Noise Ratio (SNR)	60 dB Min	60 dB Typ	60 dB Min
Channel Matching	11 LSBs Max	11 LSBs Max	10 LSBs Max
Offset Error	±6 LSBs Max	±6 LSBs Max	±4 LSBs Max
Gain Error	±0.5% Max	±0.5% Max	±0.4% Max
On-Chip Reference Variation[1]	1.25V ±1.5% Max	1.25V ±1.5% Max	1.25V ±1.0% Max

Notes:

1. See Answer Record 44971 for more information on the impact to XADC measurements when the on-chip reference source is used.

DS183, *Virtex-7 FPGAs Data Sheet: DC and Switching Characteristics* specifications will be updated to reflect the final device characterization.

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GTX Transceivers

Out-of-Band Signaling

The GTX transceiver circuitry for out-of-band (OOB) signaling is always enabled.

CPLL Power Down

The GTX transceiver CPLL can become inoperative if conditions (1) and (2) persist for more than 8,000 hours:

1. Power has been applied to MGTAVCC and MGTAVTT.
2. The device is in one of the following states:
   a. The FPGA is not configured.
   b. The FPGA is configured, but the transceiver is uninstantiated.
   c. The transceiver is instantiated, but the CPLL is held in power-down state.

When the QPLL is being used, enabling each CPLL will consume up to 30 mA on the MGTAVTT supply and 20 mA on MGTAVCC. See Answer Record 45360 for more details.

GTX Transceiver Power-Up/Power-Down

The GTX transceiver can become inoperative if MGTAVTT is within its recommended operating range and MGTAVCC is at a voltage less than 0.4V for more than 10,000 cumulative hours. An additional 100 mA per transceiver is drawn when MGTAVTT is within its recommended operating range and MGTAVCC is at a voltage less than 0.4V.

IEEE Std 1149.6 for GTX Transceivers

In the devices listed in Table 1, IEEE Std 1149.6 (ACJTAG) boundary-scan test commands EXTEST_PULSE and EXTEST_TRAIN are not supported.

Power

Static Power

All power supplies can exhibit up to 25% higher static current compared to the static current reported in XPE.

Also, up to an additional 30 mA per used transceiver, and up to an additional 50 mA per powered transceiver quad can be consumed by the MGTAVCC supply. And, up to an additional 50 mA per powered transceiver quad can be consumed by the MGTAVTT supply.

Design Software Requirements

The devices listed in Table 1, unless otherwise specified, require the following Xilinx Design Tools:

- Speed specification v1.03 (or later) of Xilinx® ISE® Design Suite 13.4 (or later) available at http://www.xilinx.com/support/download/.
- For GTX transceiver attribute updates, refer to Answer Record 45360.
- See Virtex-7 FPGA Answer Record 46345 for known issues and work-arounds for Xilinx Design Tools.

Operational Guidelines

Designs targeting DDR3 data rates above 800 Mb/s should include an external V_{REF}. For further details, refer to Answer Record 42036.

Traceability

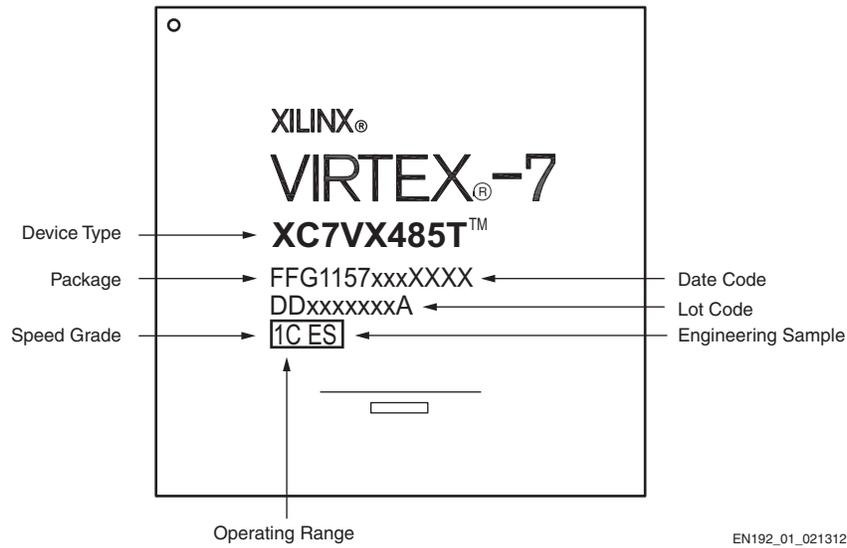Figure 1 shows an example device top mark for the devices listed in Table 1.

Figure 1: **Example Device Top Mark**

Additional Questions or Clarifications

For additional questions regarding these errata, contact Xilinx Technical Support:
http://www.xilinx.com/support/clearexpress/websupport.htm or your Xilinx Sales Representative:
http://www.xilinx.com/company/contact/index.htm.

Revision History

The following table shows the revision history for this document:

Date	Version	Description of Revisions
02/16/12	1.0	Initial Xilinx release.

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